

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method of fabricating an integrated circuit comprising:
forming or providing a metal solution, the solution also containing carbon nanotubes; and
forming a metal layer utilizing the solution.
2. (Currently Amended) The method of claim 1 wherein the solution containing carbon nanotubes comprises~~[[:]]~~ a carbon nanotube suspensions-suspension; and ~~metal ions~~.
3. (Currently Amended) The method of claim 2 wherein the carbon nanotube ~~suspensions-suspension~~ comprise-comprises single wall, arm chair carbon nanotubes.
4. (Original) The method of claim 2 wherein the solution containing carbon nanotubes further comprises a support electrolyte.
5. (Original) The method of claim 2 wherein the solution containing carbon nanotubes further comprises a reducing agent.
6. (Original) The method of claim 5 wherein the reducing agent is a reducing agent selected from the group consisting of hyphosphite, amino-borane, formaldehyde, glyoxylic acid, hydrazine and redox pairs.
7. (Original) The method of claim 6 wherein the redox pairs is a redox pair selected from the group consisting of (Ti³⁺, Ti²⁺) and (Fe²⁺, Fe³⁺).
8. (Currently Amended) The method of claim 2 wherein the solution containing carbon nanotubes further comprises a complexing ~~agents~~ agent.

9. (Original) The method of claim 8 wherein the complexing agent is a complexing agent selected from the group consisting of tartrate, citric acid and ethylenediaminetetra-acetic acid.
10. (Currently Amended) The method of claim ~~[[2]]~~ 1 wherein the metal ~~ions-solution~~ are comprises one or more metal ions selected from the group consisting of copper, silver, gold, aluminum, tin, indium, nickel, cobalt, iron, cadmium, chromium, ruthenium, rhodium, rhenium, antimony, bismuth, platinum, zinc, palladium, manganese, iridium, osmium, molybdenum, tungsten and alloys of the ~~afore-enumerated~~ afore-enumerated metals.
11. (Original) The method of claim 2 wherein the carbon nanotube suspension comprises:
a plurality of single-walled, arm chair carbon nanotubes; and
a solvent selected from the group consisting of water, ethanol, methanol and ethyleneglycol.
12. (Original) The method of claim 1 wherein said forming of the metal layer comprises electroplating a substrate using the solution.
13. (Currently Amended) The method of claim 1 wherein said forming of the metal layer comprises electroless plating of a substrate using the solution.
14. (Currently Amended) The method of claim 1 wherein said forming of the metal layer comprises ~~electrophoresis~~ electrophoretically depositing a metal layer on of a substrate using the solution.
15. (Original) The method of claim 14 further comprising annealing the electrophoresed substrate.
16. (Currently Amended) The method of claim 1 wherein said forming of the metal layer comprises spinning the solution onto ~~the~~ a substrate.

17. (Original) The method of claim 16 further comprising annealing the substrate with the spun-on solution.

18. (Original) The method of claim 1 further comprising removing excess materials.

19. (Currently Amended) The method of claim 1 further comprising ~~deposition~~ depositing of a passivation layer on the metal layer.

20-30 (Canceled)